

1 (different 9914 particles) and scanning and clean93, etc. and
2 substrate, etc. or water, etc.

☐ FSA form ☐ FSE form ☐ Other ☐ Job ☐ HTM

✓ 981 1/2 10/24/94 10/24/94

22

444

L3: (163) 2 and (different near particle\$1)
 L4: (37) 3 and (clean\$3.cim.)
 L5: (2) 4 and laser

4 and laser

Failed

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U	I	Document ID	Issue Date	Pages	Title	Current OR	Current Ref	Retrieval C	Inventor	S	C	P	I	U
1		US 20030131872	20030717	12	Water cleaning device, wafer cleaning method and chemical	134/6	134/14; 15/102;		Nishihara, Jun					U
2		US 20030027496	20030206	11	Method and apparatus for probe tip cleaning and shape	451/36	451/533		Back, Gerald W. et al.					U
3		US 20020170892	20021121	10	Dry surface cleaning apparatus using a laser	219/121.68	219/121.73; 219/121.77		Lee, Jong-Myong et al.					U
4		US 20020163637	20021107	32	Method for using an in situ particle sensor for monitoring	356/237.4	257/E21.279; 356/237.5;		Rossmann, Kent et al.					U
5		US 20020134402	20020926	17	Article produced by acoustic cavitation in a liquid inson	134/1	134/1.3		Madanshetty, Sameer I.					U
6		US 20020106631	20020815	16	Single-transducer ACIM method and apparatus	134/1	134/184		Madanshetty, Sameer I.					U
7		US 20020029456	20020314	24	Method and apparatus for removing minute particles from	204/157.15	422/136		Allen, Susan Davis					U
8		US 6635045	02 20031021	9	Dry surface cleaning apparatus using a laser	219/121.68	219/121.73; 219/121.77		Lee, Jong-Myong et al.					U
9		US 6546941	01 20030415	12	Wafer cleaning device, wafer cleaning method and chemical	134/157	134/902		Nishihara, Jun					U
10		US 6395096	01 20020528	17	Single transducer ACIM method and apparatus	134/1	134/194; 134/902;		Madanshetty, Sameer I.					U
11		US 6378534	01 20020430	25	Semiconductor wafer cleaning method	134/1.3	134/18; 134/2;		Olesen, Michael B. et al.					U
12		US 6158445	A 20001212	24	Semiconductor wafer cleaning method	134/1.3	134/2; 134/26;		Olesen, Michael B. et al.					U
13		US 6025206	A 20000215	3	Method for detecting defects	438/16	250/559.41; 257/E21.525;		Chen, Jain-Hon et al.					U
14		US 5996595	A 19991207	22	Semiconductor wafer cleaning system	134/1.3	134/2; 216/99;		Olesen, Michael B. et al.					U
15		US 5950645	A 19990914	25	Semiconductor wafer cleaning system	134/98.1	134/100.1; 134/113;		Olesen, Michael B. et al.					U
16		US 5908509	A 19990601	23	Semiconductor wafer cleaning system	134/1.3	134/2; 134/26;		Olesen, Michael B. et al.					U
17		US 5656097	A 19970812	25	Semiconductor wafer cleaning system	134/1	134/2; 134/26;		Olesen, Michael B. et al.					U
18		US 4986533	A 19910129	83	Method for deposition of silicon oxide on a wafer	427/563	427/294; 427/572;		Freeman, Dean W. et al.					U
19		US 4910643	A 19900320	31	Processing apparatus and	427/563	113/722;		Freeman, Dean W. et al.					U

no Change Status

Ready

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